35.0 x 5.0 x 4.0 (mm) LTE FullBand PCB Substrate Antenna (EVB+CC35D8)Engineering Specification

1. **Product Number**

2 2 Η В M H A F 0 1



2. **Features**

- * Compatible with LTE full-band/3G/2G
- * Stable and reliable in performances
- * Compact size
- * RoHS2.0 compliance
- * SMT processes compatible

3. **Applications**

* LTE full-band/3G/2G.

* LTE / GSM / CDMA /DCS /PCS / WCDMA / UMTS / HSDPA / GPRS / FOGE / MATS

Unictron Technologies Corp.



詠業科技股份有限公司

Unictron Technologies Corporation Website:www.unictron.com

THIS DRAWINGS AND SPECIFICATIONS ARESTHE PROPERTY OF UNICTRON TECHNOLOGIES CORPORATION AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR DEVICES WITHOUT **PERMISSION**

Prepared by : Wen Designed by: Allen Checked by: Mike Approved by : Herbert

TITLE: 35.0 x 5.0 x 4.0 (mm) LTE FullBand PCB

Substrate Antenna (EVB+CC35D8) **Engineering Specification**

NO.

DOCUMENT

H2B1MH2A2F0100

REV. Α

4. Description

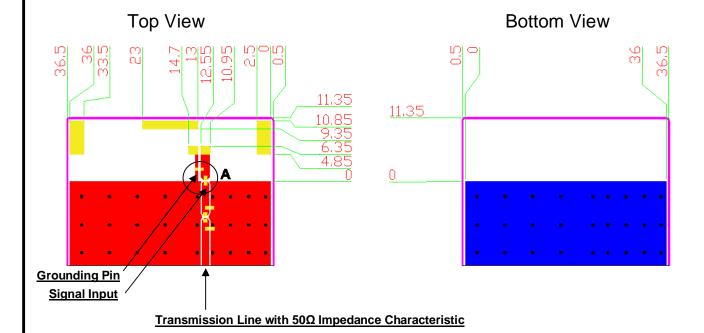
Unictron's CC35D8 ceramic chip antenna is designed for cellular 2G/3G/LTE bands applications, covering frequencies 698~960 MHz & 1710~2690 MHz. Fabricated with proprietary design and processes, CC35D8 shows excellent performance and is fully compatible with SMT processes which can decrease the assembly cost and improve device's quality and consistency.

5. Layout Guide & Electrical Specifications

5-1. Layout Guide (Unit: mm)

Solder Land Pattern:

The solder land pattern (gold marking areas) is shown below. Recommendation on matching circuit will be provided according to customer's installation conditions.



Unictron Technologies Corp.

2018-09-20

Unictron Technologies Corp.

詠業科技股份有限公司

Unictron Technologies Corporation Website:www.unictron.com

THIS DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF UNICTRON TECHNOLOGIES CORPORATION AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR DEVICES WITHOUT PERMISSION

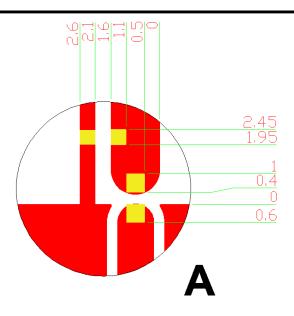
Prepared by : Wen Designed by : Allen Checked by : Mike Approved by : Herbert

TITLE: 35.0 x 5.0 x 4.0 (mm) LTE FullBand PCB Substrate Antenna (EVB+CC35D8)

Engineering Specification

DOCUMENT NO.

H2B1MH2A2F0100



5-2. Electrical Specifications (with 118.5 x 37 mm² Evaluation Board) 5-2-1. Electrical Table

Characteristics	Specifications				
Outline Dimension (mm)	35.0 x 5.0 x 4.0				
Ground Plane Dimension (mm)	107.1 x 37				
Working Frequency (MHz)	698 ~ 798	824 ~ 960	1710 ~ 2170	2300 ~ 2400	2490 ~ 2690
Peak Gain (dBi) (typical)**	1.3	1.0	2.6	4.4	4.2
Efficiency (%) (typical)**	54	58	55	75	65
VSWR (@ center frequency)*	<3.5:1				
Characteristic Impedance (Ω)	50				
Polarization	Linear Polarization				

^{*}Center frequency means the frequency with the lowest value in return loss of the chip antenna on the evaluation board.

Unictron Technologies Corp.

2018-09-20

A

Unictron Technologies Corp.

Engineering Specification

詠業科技股份有限公司

Unictron Technologies Corporation Website:www.unictron.com

THIS DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF UNICTRON TECHNOLOGIES CORPORATION AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR DEVICES WITHOUT PERMISSION

Prepared by : Wen Designed by : Allen Checked by : Mike Approved by : Herbert

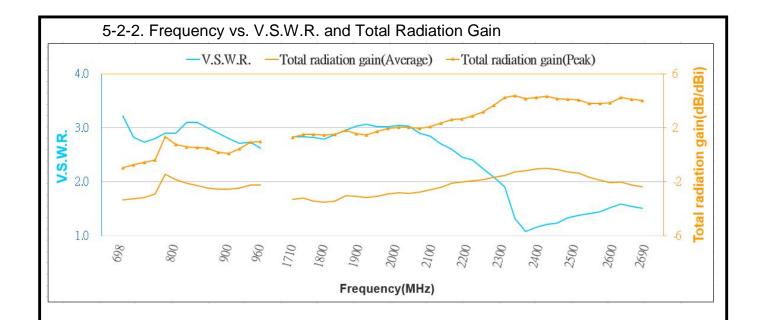
TITLE: 35.0 x 5.0 x 4.0 (mm) LTE FullBand PCB
Substrate Antenna (EVB+CC35D8)

DOCUMENT
H2B1MH2A2F0100

NO.

PAGE 3 **OF** 15

^{**}A typical value is for reference only, not guaranteed.



Unictron Technologies Corp.

2018-09-20



詠業科技股份有限公司

Unictron Technologies Corporation Website:www.unictron.com

THIS DRAWINGS AND SPECIFICATIONS ARESTHE PROPERTY OF UNICTRON TECHNOLOGIES CORPORATION AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR DEVICES WITHOUT **PERMISSION**

Prepared by : Wen Designed by : Allen Checked by : Mike Approved by : Herbert

TITLE: 35.0 x 5.0 x 4.0 (mm) LTE FullBand PCB

Substrate Antenna (EVB+CC35D8)

Engineering Specification

DOCUMENT NO.

H2B1MH2A2F0100

REV. A

15 PAGE 4 OF

Outline Dimensions of Antenna & Evaluation Board (Unit: mm) 6. 6-1. Antenna Dimensions A 35±2 **Top View** Unictron **Front View** (1.65)**Bottom View Back View** NOTE: 1.All materials are RoHS 2.0 compliant. 2." A~©" Critical Dimensions. 3."()" Reference Dimensions. Unictron Technologies Corp. 2018-09-20 THIS DRAWINGS AND SPECIFICATIONS ARESTHE PROPERTY OF UNICTRON TECHNOLOGIES 詠業科技股份有限公司 CORPORATION AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR **Unictron Technologies Corporation** SALE OF APPARATUS OR DEVICES WITHOUT Technologies Corp. Website:www.unictron.com **PERMISSION**

Prepared by : Wen Designed by : Allen Checked by : Mike Approved by : Herbert

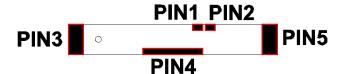
TITLE: 35.0 x 5.0 x 4.0 (mm) LTE FullBand PCB DOCUMENT

Substrate Antenna (EVB+CC35D8)
Engineering Specification

NO.

H2B1MH2A2F0100

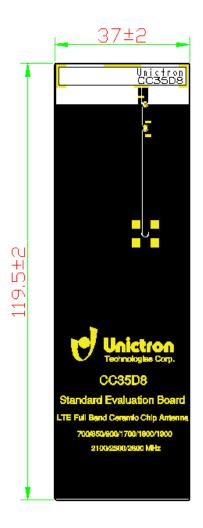
PIN Definition

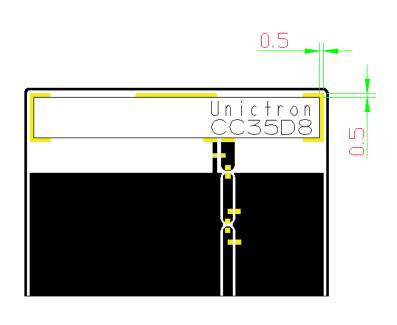


Bottom View

PIN	1	2	3~5
Soldering Pad	Tuning/Ground	Signal	N/C

6-2. Evaluation Board & Antenna Location





Unit: mm

Unictron
Technologies Corp.

2018-09-20

Unictron Technologies Corp.

詠業科技股份有限公司

Unictron Technologies Corporation Website:www.unictron.com

THIS DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF UNICTRON TECHNOLOGIES CORPORATION AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR DEVICES WITHOUT PERMISSION

Prepared by : Wen Designed by : Allen Checked by : Mike Approved by : Herbert

TITLE: 35.0 x 5.0 x 4.0 (mm) LTE FullBand PCB

Substrate Antenna (EVB+CC35D8)

Engineering Specification

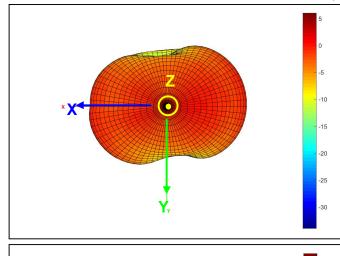
DOCUMENT NO.

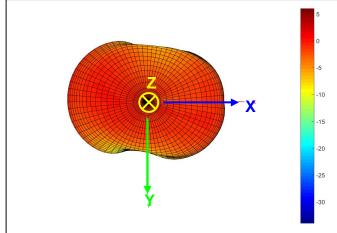
H2B1MH2A2F0100

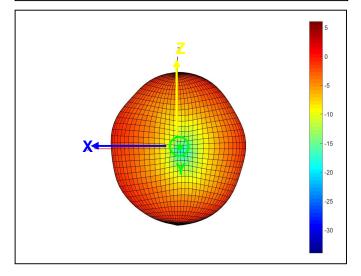
7. 3D Radiation Gain Pattern (with 118.5 x 37 mm² Evaluation Board)

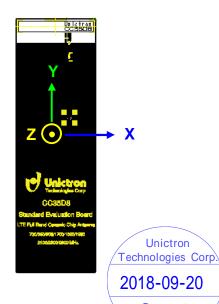
7-1. 698~798MHz Band

3D Radiation Gain Pattern @ 748 MHz (Unit: dBi)











詠業科技股份有限公司

Unictron Technologies Corporation Website:www.unictron.com

THIS DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF UNICTRON TECHNOLOGIES CORPORATION AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR DEVICES WITHOUT PERMISSION

Prepared by : Wen Designed by : Allen Checked by : Mike Approved by : Herbert

TITLE: 35.0 x 5.0 x 4.0 (mm) LTE FullBand PCB DOCUMENT

Substrate Antenna (EVB+CC35D8)
Engineering Specification

NO.

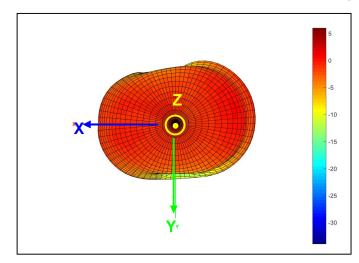
H2B1MH2A2F0100

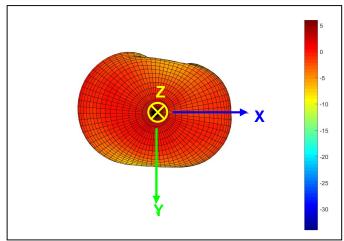
REV.

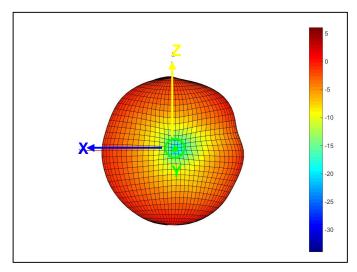
PAGE 7 **OF** 15

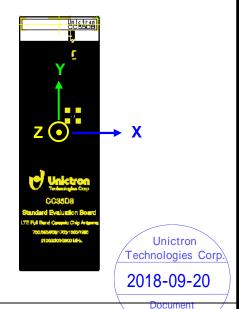
7-2. 824~960MHz Band

3D Radiation Gain Pattern @ 890 MHz (Unit: dBi)











詠業科技股份有限公司

Unictron Technologies Corporation Website:www.unictron.com

THIS DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF UNICTRON TECHNOLOGIES CORPORATION AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR DEVICES WITHOUT PERMISSION

Prepared by : Wen Designed by : Allen Checked by : Mike Approved by : Herbert

TITLE: 35.0 x 5.0 x 4.0 (mm) LTE FullBand PCB

Substrate Antenna (EVB+CC35D8) Engineering Specification

DOCUMENT NO.

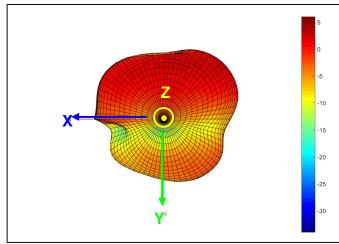
H2B1MH2A2F0100

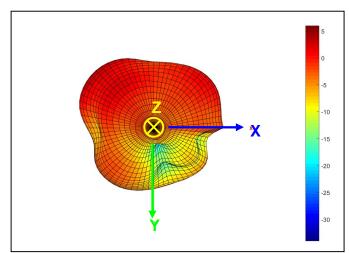
REV.

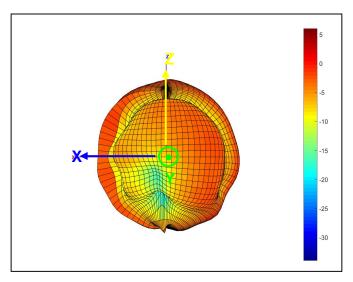
PAGE 8 **OF** 15

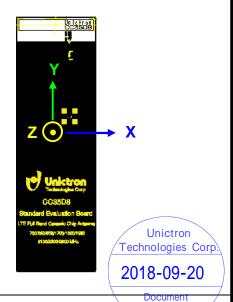
7-3. 1710~2170MHz Band

3D Radiation Gain Pattern @ 1950 MHz (Unit: dBi)











詠業科技股份有限公司

Unictron Technologies Corporation Website:www.unictron.com

THIS DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF UNICTRON TECHNOLOGIES CORPORATION AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR DEVICES WITHOUT PERMISSION

Prepared by : Wen Designed by : Allen Checked by : Mike Approved by : Herbert

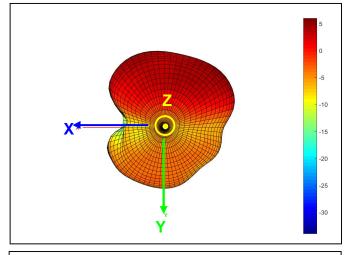
TITLE: 35.0 x 5.0 x 4.0 (mm) LTE FullBand PCB Substrate Antenna (EVB+CC35D8)

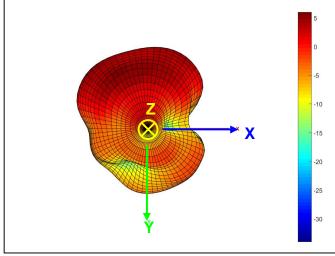
Substrate Antenna (EVB+CC35D8) Engineering Specification DOCUMENT NO.

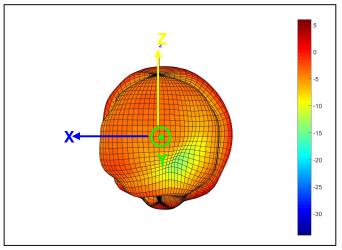
H2B1MH2A2F0100

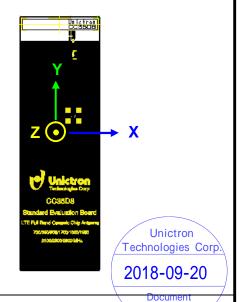
7-4. 2300~2400MHz Band

3D Radiation Gain Pattern @ 2350 MHz (Unit: dBi)











詠業科技股份有限公司

Unictron Technologies Corporation Website:www.unictron.com

THIS DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF UNICTRON TECHNOLOGIES CORPORATION AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR DEVICES WITHOUT PERMISSION

Prepared by : Wen Designed by : Allen Checked by : Mike Approved by : Herbert

TITLE: 35.0 x 5.0 x 4.0 (mm) LTE FullBand PCB

Substrate Antenna (EVB+CC35D8) Engineering Specification DOCUMENT NO.

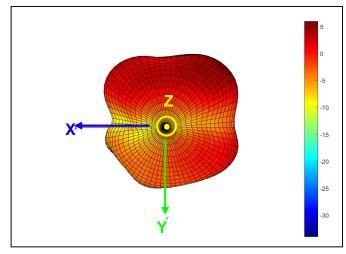
H2B1MH2A2F0100

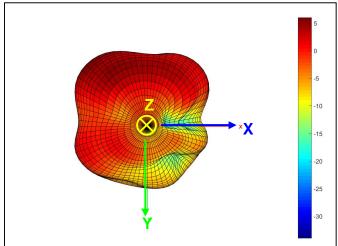
REV.

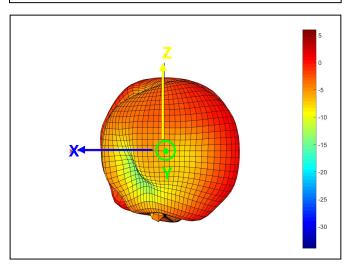
PAGE 10 **OF** 15

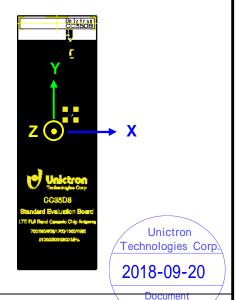
7-5. 2490~2690MHz Band

3D Radiation Gain Pattern @ 2590 MHz (Unit: dBi)











詠業科技股份有限公司

Unictron Technologies Corporation Website:www.unictron.com

THIS DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF UNICTRON TECHNOLOGIES CORPORATION AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR DEVICES WITHOUT PERMISSION

Prepared by : Wen Designed by : Allen Checked by : Mike Approved by : Herbert

TITLE: 35.0 x 5.0 x 4.0 (mm) LTE FullBand PCB Substrate Antenna (EVB+CC35D8)

Engineering Specification

DOCUMENT NO.

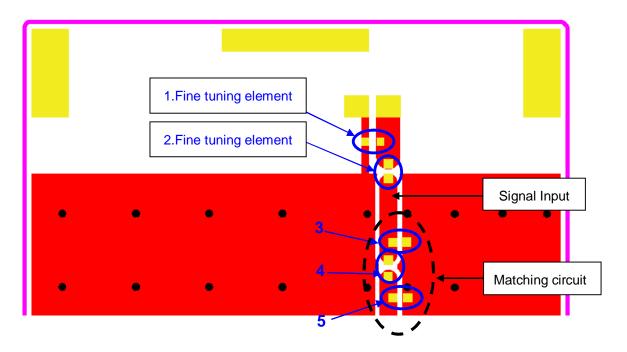
H2B1MH2A2F0100

REV.

PAGE 11 **OF** 15

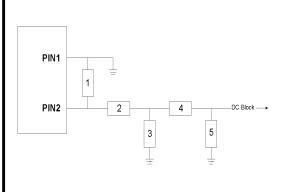
8. Frequency tuning and Matching circuit

8-1. Chip antenna tuning scenario:



8-2. Matching circuit:

With the following recommended values of matching and tuning components, the covering frequencies will be about $698\sim960$ MHz & $1710\sim2690$ MHz at our standard 118.5×37 mm² evaluation board. However, these are typical reference values which may need to be changed when circuit boards or part vendors are different.



System Matching Circuit Component					
Location	Description	Vendor	Tolerance		
1 Fine tuning element	6.8 nH, (0402)	MURATA	±0.1 nH		
2 Fine tuning element	3.9 pF, (0402)	MURATA	±0.05 pF		
3	N/C	-	-		
4	0Ω, (0402)	- Tech	Unictron		
5	N/C	10011	8-09-20		



詠業科技股份有限公司

Unictron Technologies Corporation Website:www.unictron.com

THIS DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF UNICTRON TECHNOLOGIES CORPORATION AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR DEVICES WITHOUT PERMISSION

Prepared by : Wen Designed by : Allen Checked by : Mike Approved by : Herbert

TITLE: 35.0 x 5.0 x 4.0 (mm) LTE FullBand PCB Substrate Antenna (EVB+CC35D8)

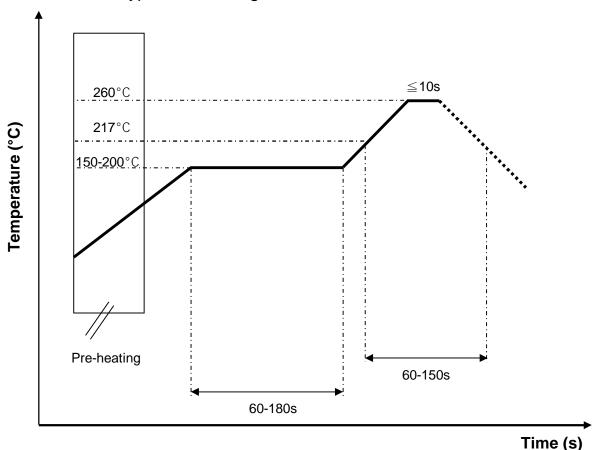
Engineering Specification

DOCUMENT NO.

H2B1MH2A2F0100

9. Soldering Conditions

Typical Soldering Profile for Lead-free Process



*Recommended solder paste alloy: SAC305 (Sn96.5 /Ag3 /Cu0.5) Lead Free solder paste

10. Reminders for users of Unictron's CC35D8 ceramic chip antennas

- 10-1. This chip antenna is made of ceramic materials which is relatively more rigid and brittle compared to circuit board materials. Furthermore, the length of this antenna is quite long. Bending of circuit board at the locations where chip antenna is mounted may cause the cracking of solder joints or antenna itself.
- 10-2. Punching/cutting of the break-off tab of PCB panel may cause severe bending of the circuit board which may result in cracking of solder joints or chip antenna itself. Therefore break-off tab shall be located away from the installation site of chip antenna.
- 10-3. Be cautious when ultrasonic welding process needs to be used near the locations where chip antennas are installed. Strong ultrasonic vibration may cause the cracking of chip antenna solder joints.



詠業科技股份有限公司

kaictron Technologies Corporation ଞ୍ରିଟି Website:www.unictron.com

THIS DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF UNICTRON TECHNOLOGIES CORPORATION AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR DEVICES WITHOUT PERMISSION

Prepared by : Wen Designed by : Allen Checked by : Mike Approved by : Herbert

TITLE: 35.0 x 5.0 x 4.0 (mm) LTE FullBand PCB

Substrate Antenna (EVB+CC35D8) Engineering Specification

DOCUMENT NO.

H2B1MH2A2F0100

11. **Operating & Storage Conditions**

11-1. Operating

(1) Maximum Input Power: 5 W

(2) Operating Temperature: -40°C to 85°C

(3) Relative Humidity: 10% to 70%

11-2. Storage (sealed)

(1) Storage Temperature: -5°C to 40°C

(2) Relative Humidity: 20% to 70%

(3) Shelf Life: 1 year

12. Notice

(1) Installation Guide:

Please refer to Unictron's application note "General guidelines for the installation of Unictron's chip antennas" for further information.

(2) All specifications are subject to change without notice.

Unictron Technologies Corp.

2018-09-20

詠業科技股份有限公司

Unictron Technologies Corporation Website:www.unictron.com

THIS DRAWINGS AND SPECIFICATIONS ARESTHE PROPERTY OF UNICTRON TECHNOLOGIES CORPORATION AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR DEVICES WITHOUT PERMISSION

Prepared by : Wen Designed by: Allen Checked by : Mike Approved by : Herbert

TITLE: 35.0 x 5.0 x 4.0 (mm) LTE FullBand PCB **DOCUMENT**

Substrate Antenna (EVB+CC35D8)

Engineering Specification

NO.

H2B1MH2A2F0100

REV. Α

PAGE 14 15

13. Reliability Test

Test Items Test Conditions		Result	
1. Solderability	*Solder Temperature : 250 ± 5°C		
	*Test time: 2 +/- 0.5 sec	Pass	
	*With solder paste		
2. Temperature cycling	-40°C/ 30min~90°C /30min		
	Total 10 cycles		
	* Specimens are kept at standard	Pass	
	measurement environment for more than 24		
	hours before testing.		
3. Damp heat	*Humidity:90~95%		
	*Temperature: 85°C		
	*Test time: 240 hours	Pass	
	* Specimens are kept at standard	Pass	
	measurement environment for more than 24		
	hours before testing		
4. Adhesive strength of	* Resistance to bending of printed-circuit		
terminal electrodes	test board(110x40x1.6mm)	Pass	
	* Applied force: 5Kgf;	F a 5 5	
	* Duration: 10±1sec		
5. High temperature exposure	*Temperature : 90°C		
	*Test duration: 240 hours		
	* Specimens are kept at standard	Pass	
	measurement environment for more than 24		
	hours before testing.		
6. Low temperature exposure	*Temperature : -40°C		
	*Test duration: 240 hours		
	* Specimens are kept at standard Pass		
	measurement environment for more than 24		
	hours before testing.		

Unictron Technologies Corp.

2018-09-20



詠業科技股份有限公司

Unictron Technologies Corporation Website:www.unictron.com

THIS DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF UNICTRON TECHNOLOGIES CORPORATION AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR DEVICES WITHOUT PERMISSION

Prepared by : Wen Designed by : Allen Checked by : Mike Approved by : Herbert

TITLE: 35.0 x 5.0 x 4.0 (mm) LTE FullBand PCB DOCUMENT

Substrate Antenna (EVB+CC35D8)
Engineering Specification

NO.

H2B1MH2A2F0100